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S	pecification				
Part Number:					
Version:					
Date:					
Revision					

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1.General Specification

The Features is described as follow:

- Module dimension: 115.0 x 36.0 x 13.9 (MAX) mm
- View area: 85.0 x 18.6 mm
- Active area: 73.5 x 11.5 mm
- Number of Characters: 20 characters x 2 Lines
- Dot size: 0.60 x 0.65 mm
- Dot pitch: 0.65 x 0.70 mm
- Character size: 3.20 x 5.55 mm
- Character pitch: 3.70 x 5.95 mm
- LCD type: VA Negative Transmissive
- Duty: 1/16
- View direction: 12 o'clock
- Backlight Type: LED, High light White
- IC:ST7060gn manufacture supply

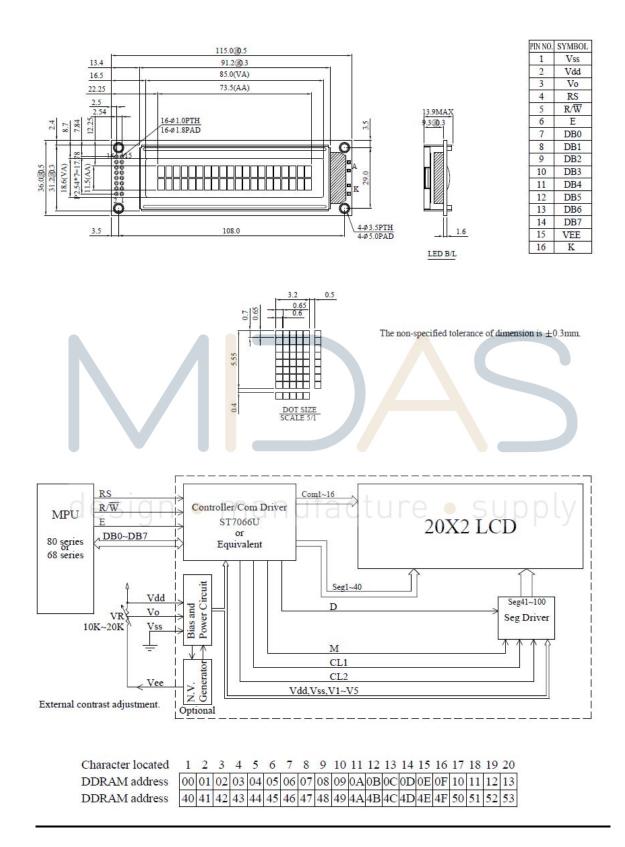
Midas LCD Part Number System

МС	COG	132033	Α	*	6	w	*	*	-	S	Ν	т	L	w	*	*
1	2	3	4	5	6	7	8	9	-	10	11	12	13	14	15	16
1	=	MC: Midas	Compor	nents												
2	=	Blank: COF	B (chip o	on boai	rd) CO	G: chip	on glas	s								
3	=	No of dots		(e.g. 24	40064	= 240 x	64 dot	s)	(e	.g. 216	05 = 2	x 16 5m	m C.H.))		
4	=	Series														
5	=	Series Varia	int:	A to Z	– see :	addendı	ım									
6	=	3: 3 o'clock		6: 6 o'	clock	9): 9 o'cl	ock	12	2:12 o'	clock					
7	=	S: Normal (0 to + 5	50 deg (C) W:	Wide to	emp. (-	20 to +	- 70 de	g C) X:	Exten	ded tem	np (-30 +	+ 80 De	gC)	
8	=	Character S	et													
9	=	Blank 9 2 8 3 7 4 7 5 9 6 7 7 8 9 6 A 5 B 5 D 6 E 5 F 4	Simplifi Big 5 (n (std) Japanes in (Eng an (Eng n (Engl abic nt (wher to (wher to p of H	ed (Gra Graph (Englis (e (spec lish/Sca lish/Gr lish/Gr e appli Bezel to PCB not	aphic I ic Disp sh/Gerr cial) andina reek) andina	Displays on man/Fr vian/Ic / availal (via an (via an Con Sep Con Sep Con Sep Con Sep Con Sep Con Sep Con Sep Con Sep Con Sep	ly) ench/G elandic) Arr or l I Arr Arr Arr Arr Arr Ec Ec Ec Ec Ec Ec Ec Ec Ec	ray Edge .it ray ray ray ray ray ray ray dge dge dge dge dge L				SU		ly	
10	=	T: TN S : S'	ΓN B : S	STN B	lue G:	STN G	rey F:	FSTN	F2: F	FSTN	V: VAT	FN Z:2	Zero Po	wer (Bi-	Stable))
11	=	P: Positive	N: Neg	ative												
12	=	R: Reflectiv	ve M: T	'ransmi	issive	T: Tran	sflectiv	ve								
13	=	Backlight:	Blank:	Reflect	tive L	: LED										
14	=	Backlight C	olour:	Y: Yel	low-G	reen W	: White	e B: Bl	lue R:	Red A	: Ambe	er 0: O1	ange G :	Green	RGB: 1	R.G.B.
		If Z (Zero I	Power):	WB: W	White o	on blue	GB: G1	reen on	l black	YB: Y	ellow o	n black	YPB: Y	Yellow o	on pink	and/or blue
15	=	Driver Chip	:	Blank	: Stand	dard I	: I ² C	T: Tos	hiba T	6963C	A: Av	ant SA	P1024B	R: R	aio RA	.8835
16	=	Voltage Va	r iant : e.	g. 3 = 3	Bv											

3.Interface Pin Function

Pin No.	Symbol	Level	Description
1	V_{SS}	0V	Ground
2	V_{DD}	5.0V	Supply Voltage for logic
3	VO	(Variable)	Operating voltage for LCD
4	RS	H/L	H: DATA, L: Instruction code
5	R/W	H/L	H: Read (Module> MPU) L: Write(MPU> Module)
6	E	H,H→L	Chip enable signal
7	DB0	H/L	Data bus line
8	DB1	H/L	Data bus line
9	DB2	H/L	D <mark>at</mark> a bus line
10	DB3	H/L	D <mark>at</mark> a bus line
11	DB4	H/L	Data bus line
12	DB5	H/L	Data bus line
13	DB6	H/L	Data bus line
14	DB7	H/L	Data bus line
15	Vee		Negative Voltage Output
16	К		Power supply for B/L -

4.Contour Drawing & Block Diagram



5.Character Generator ROM Pattern

Table.2

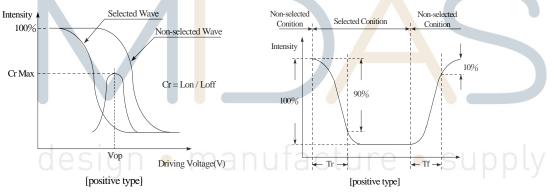
Upper																
4 bit Lower 4 bit	LLLL	LLLH	LLHL	LLHH	LHLL	LHLH	LHHL	LHHH	HLLL	HLLH	HLHL	HLHH	HHLL	HHLH	HHHL	нннн
LLLL	CG RAM (1)						•••	₽					-]]		Ċ.	¦∷ ∙
LLLH	(2)							•:::-					Ţ.	 		•
LLHL	(3)							ŀ			1	•	! <u>.</u> !		 :	I <u></u> I
LLHH	(4)					::	:	·,				:		•	: <u>.</u>	::-: *
LHLL	(5)			÷.				·			٠.,				I	::::
LHLH	(6)					I!		II					÷		:	II
LHHL	(7)					I.,I	÷	۱. _. .۱							l::	
LHHH	(8)			÷				II			·			····	.	:]:
HLLL	(1)	de	sl	n	•••		a-n	Uf	ac	tu	re	••••	SU		p . ty	
HLLH	(2)		2			۰, I		·!			-	·]]			!	ا <u>…</u> ا
HLHL	(3)		:•[+:	:: ::	•									.	i	:: :]
HLHH	(4)			:	Þť.		ŀ:	÷			?†				:-:]==
HHLL	(5)		:	÷.		÷					17			·	·: :-	:::
HHLH	(6)		•••••				[``	}					·`•;	 •	: ! :	
HHHL	(7)				ŀ··		ŀ"1							••••	ŀ"ı	
нннн	(8)							•			••	ا۔ ۔۔۔	·.:		ı <u></u> ı	

6.Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
	θ	CR≧10	_	60	_	ψ= 180°
View Angle	θ	CR≧10	_	25	_	ψ= 0°
View Angle	θ	CR≧10	_	40		ψ= 90°
	θ	CR≧10		40		ψ= 270°
Contrast Ratio	CR	_	10	_	_	—
Deenenee Time	T rise	_	_	300	350	ms
Response Time	T fall	_		300	350	ms

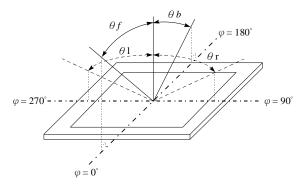
Definition of Operation Voltage (Vop)

Definition of Response Time (Tr, Tf)



Conditions :

Definition of viewing angle(CR≥2)



7.Absolute Maximum Ratings

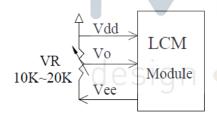
Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	T _{OP}	-20	_	+70	
Storage Temperature	T _{ST}	-30		+80	
Input Voltage	VI	V _{SS}		V _{DD}	V
Supply Voltage For Logic	VDD-V _{SS}	-0.3		7	V
Supply Voltage For LCD	V _{DD} -V _o	-0.3	_	13	V



8.Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	V_{DD} - V_{SS}	_	4.5	5.0	5.5	V
Supply Voltage For LCD		Ta=-20°C	_		_	V
*Note	V_{DD} - V_0	Ta=25°C	8.2	8.5	8.8	V
		Ta=70°C	_			V
Input High Volt.	V _{IH}	_	$0.7 V_{DD}$		V _{DD}	V
Input Low Volt.	V _{IL}	_	Vss		0.6	V
Output High Volt.	V _{OH}		3.9		V _{DD}	V
Output Low Volt.	V _{OL}	-	0	_	0.4	v
Supply Current	I _{DD}	$V_{DD}=5.0V$	-	1.0	_	mA

*Note: Please design the VOP adjustment circuit on customer's main board



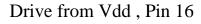
manufacture • supply

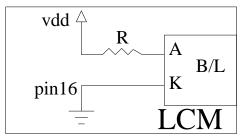
9.Backlight Information

Specification

PARAMETER	SYMBOL	MIN	ТҮР	МАХ	UNIT	TEST CONDITION
Supply Current	ILED	_	48	60	mA	V=5.0V
Supply Voltage	V	4.9	5.0	5.1	v	_
Reverse Voltage	VR	_	_	5	v	_
Luminance (Without LCD)	IV	560	700	_	CD/M ²	ILED=48mA
LED Life Time (For Reference	_	_	50K	_	Hr.	ILED=48mA 25 ,50-60%RH,
` only)						(Note 1)
Color	White(hig	h <mark>li</mark> ght)				

- Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).
- Note 1:50K hours is only an estimate for reference.





10.Reliability

Content of Reliability Test (Wide temperature, -20 ~70)

	Environmental Test		
Test Item	Content of Test	Test Condition	Note
High Temperature storage	Endurance test applying the high storage temperature for a long time.	200hrs	2
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70 200hrs	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20 200hrs	1
High Temperature/ Humidity storage	The module should be allowed to stand at 60 ,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60 ,90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20 25 70	-20 /70 10 cycles	
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude : 1.5mm Vibration Frequency : 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS=1.5kΩ CS=100pF 1 time	

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal

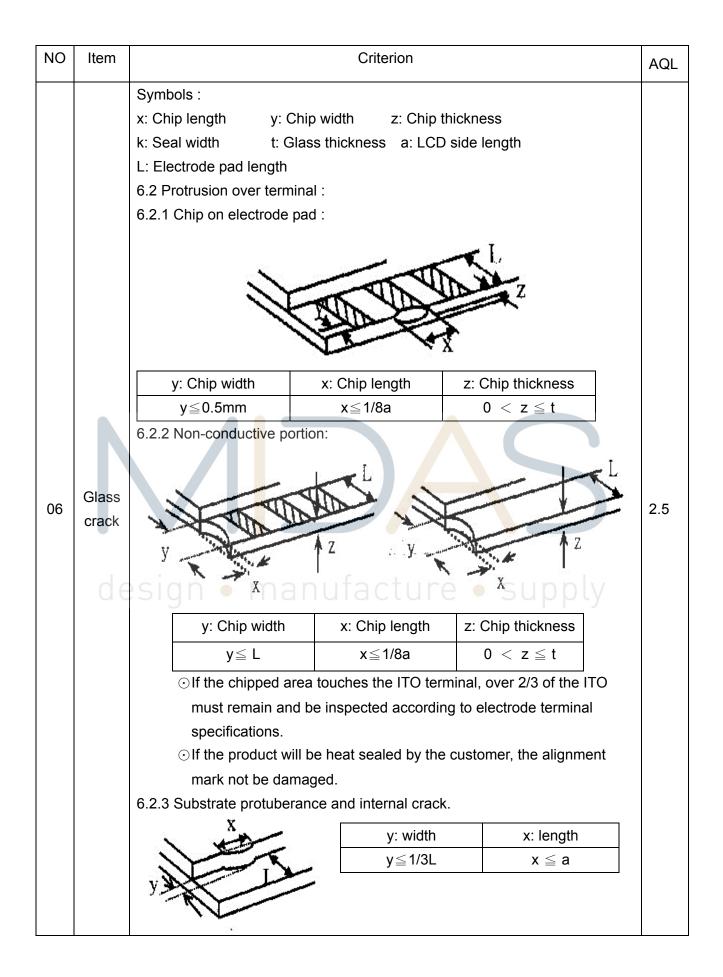
Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

11.Inspection specification

NO	Item		Criterion		AQL			
01	Electrical Testing	 1.3 Display malfunction. 1.4 No function or no disp 1.5 Current consumption 	defect. 1.2 Missing character , dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect.					
02	Black or white spots on LCD (display only)	 2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm 						
03	LCD black spots, white spots, contamination (non-display)		SIZE $\Phi \leq 0.10$ $0.10 < \Phi \leq 0.20$ $0.20 < \Phi \leq 0.25$ $0.25 < \Phi$	Acceptable Q TY Accept no dense 2 1 0 SUDDU Acceptable Q TY Accept no dense 2 As round type	2.5			
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.	Size Φ $\Phi \leq 0.20$ $0.20 < \Phi \leq 0.50$ $0.50 < \Phi \leq 1.00$ $1.00 < \Phi$ Total Q TY	Acceptable Q TY Accept no dense 3 2 0 3 3	2.5			

NO	Item		Criterion		AQL				
05	Scratches	Follow NO.3 LCD black	spots, white spots, cor	ntamination					
	Scratches	Symbols Define: x: Chip length y: 0 k: Seal width t: 0 L: Electrode pad length 6.1 General glass chip 6.1.1 Chip on panel sur $\begin{bmatrix} z: Chip thickness \\ Z \leq 1/2t \end{bmatrix}$ $1/2t < z \leq 2t$	chip width z: Chip Glass thickness a: LCI face and crack betweer y: Chip width Not over viewing area Not exceed 1/3k chips, x is total length	thickness D side length n panels: x : Chip length $x \le 1/8a$ of each chip.	2.5				
	⊙ If there are 2 or more chips, x is the total length of each chip.								



NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB · COB desig	 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB 	 2.5 2.5 0.65 2.5 0.65 0.65 2.5 2.5 2.5 2.5 2.5
11	Soldering	 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. 	2.5 2.5 2.5 0.65

NO	Item	Criterion				
	General appearance	12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.				
		12.2 No cracks on interface pin (OLB) of TCP.12.3 No contamination, solder residue or solder balls on product				
		12.4 The IC on the TCP may not be damaged, circuits.	2.5 2.5			
		12.5 The uppermost edge of the protective strip on the interface				
		pin must be present or look as if it cause the interface pin to				
12		sever. 12.6 The residual rosin or tin oil of soldering (component or chip				
		component) is not burned into brown or black color.				
		12.7 Sealant on top of the ITO circuit has not hardened.12.8 Pin type must match type in specification sheet.				
		12.9 LCD pin loose or missing pins. 12.10 Product packaging must the same as specified on				
		packaging specification sheet. 12.11 Product dimension and structure must conform to product				
		specification sheet.				
		12.12 Visual defect outside of VA is not considered to be rejection				

12.Precautions in use of LCD Modules

- (1)Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6)Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.
- (8) T aaæ have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors,capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9)T a have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, T a have the right to modify the version.)

13.Material List of Components for RoHs

1. T a Display Co., Ltd hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A : The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs		
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm		
Above liested velve is estimated and the Dello								

Above limited value is set up according to RoHS.

2.Process for RoHS requirement :

- (1) Use the Sn/Ag/Cu soldering surface ; the surface of Pb-free solder is rougher than we used before.
- (2) Heat-resistance temp. :

Reflow: 250 ,30 seconds Max.;

Connector soldering wave or hand soldering : 320 , 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235±5 ;

Recommended customer's soldering temp. of connector : 280 , 3 seconds.

14.Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.

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